

Pos.	Ref Des	Number per board	Description	DigiKey part #	Comment
1	C1, C2	0	12pF, SMD0805		DNP: C1, C2
1.1	C3, C4	0	47pF, SMD0805		DNP: C3, C4
2	C6, C7, C10, C12	3	10uF/6.3V, SMD0805		DNP C10
3	C5, C11, C13, C14, C15	5	100nF, SMD0805	311-1245-2-ND	
4	C8	1	2.2nF, SMD0805		
5	C9	1	470nF, SMD0805	478-1403-2-ND	
6	C16	1	4.7 uF, SMD0805		
7	C17	1	220 nF, SMD0805		
8	D1	1	green LED, SMD0805	P516TR-ND	
9	J1, J2, J3, J4	4	20-pin header, TH	SAM1029-20-ND	DNP: headers and receptacles enclosed with kit. Keep vias free of solder. : Header : Receptacle
9.1		4	20-pin header, TH	SAM1213-20-ND	DNP: headers and receptacles enclosed with kit. Keep vias free of solder. : Header : Receptacle
10	J5, J6	2	3-pin header, male, TH	SAM1035-03-ND	
11	JP5, JP6, JP7, JP8, JP9, JP10	6	3-pin header, male, TH	SAM1035-03-ND	place jumpers on pins 2-3
12	JP1, JP2; JP4	3	2-pin header, male, TH	SAM1035-02-ND	place jumper on header
13	JP3	1	3-pin header, male, TH	SAM1035-03-ND	place jumper on pins 1-2
14		10	Jumper	15-38-1024-ND	Place on: JP1, JP2, JP3, JP4, JP5, JP6, JP7, JP8, JP9, JP10
15	JTAG	1	14-pin connector, male, TH	HRP14H-ND	
16	Q1	0	Crystal	Micro Crystal MS3V-T1R 32.768kHz, C(Load) = 12.5pF	DNP: Q1 Keep vias free of solder
17	Q2	1	Crystal	Q2: 4MHz Buerklin: 78D134	DNP: Q2 Keep vias free of solder
18	D3, D4	2	LL103A	Buerklin: 24S3406	
19	R3, R7	2	330 Ohm, SMD0805	541-330ATR-ND	
20	R1, R2, R4, R6, R8, R9, R10, R11, R12	3	0 Ohm, SMD0805	541-000ATR-ND	DNP: R6, R8, R9, R12, R10, R11
21	R5	1	47k Ohm, SMD0805	541-47000ATR-ND	
22	U1	1	Socket:IC201-0804-014		Manuf.: Yamaichi
23	PCB	1	77 x 91 mm		2 layers
24	Rubber stand off	4		Buerklin: 20H1724	apply to corners at bottom side
25	MSP430	2	MSP430F5329IPN		DNP: enclosed with kit. Is supplied by TI
26	IsolierScheibe zu Q2	1	IsolierScheibe zu Q2	http://www.ettlinger.de/Art_Detail.cfm?ART_ARTNUM=70.08.121	